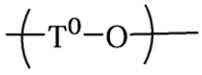
COMPOSITION FOR FORMING PASSIVATION FILM, INCLUDING RESIN HAVING CARBON-CARBON MULTIPLE BOND

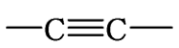
ABSTRACT

There is provided a composition for forming a passivation film that satisfies electric insulation, heat-tolerance, solvent-tolerance, and a dry etch back property at the same time. A composition for forming a passivation film, comprising: a polymer containing a unit structure of Formula (i):

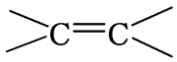


Formula (i)

(where T^0 is a sulfonyl group, a fluoroalkylene group, a cycloalkylene group, or an arylene group having a substituent, or is a combination of an arylene group optionally having a substituent and a fluoroalkylene group or a cycloalkylene group), wherein the polymer has at least one of a group having a structure of Formula (2-A), a group having a structure of Formula (2-B), or a group having both of the structures, at an end, in a side chain, or in a main chain of the polymer:



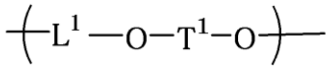
Formula (2-A)



Formula (2-B)

.

The polymer may contain a unit structure of Formula (1):



Formula (1)

.

[No accompanying figure]